

Unable to view the images in this email? [Click here](#) to view it on the Web.



Fonon DSS Announces the FiberTower™ DFAS IC Chip Package Failure Analysis System

Lake Mary, FL, February 13, 2009 - Fonon DSS (Display & Semiconductor Systems), the cutting edge developer of state-of-the-art, laser scribing, dicing, marking, coating removal, direct patterning, and photo mask repair solutions to the Flat Panel Display (FPD), Semiconductor, Photovoltaic and Electronics industries throughout the world announced today the release of [the improved FiberTower™ DFAS IC chip package failure analysis system](#).



The FiberTower™ DFAS uses laser technology to allow an operator to remove individual layers of the mold compound all the way through to the substrate. The DFAS operator can choose to remove the entire compound, individual layers, or sections of the mold compound ranging from the entire sample to just one wire due to the precision of the laser spot positioning. The FiberTower™ DFAS can import images from a variety of testing processes such as SAM, X-Ray, and SEM to show the operator exactly the area of concern within the sample.

Most failure analysis labs use time consuming chemical and mechanical etching processes on a routine basis to dissect chips to see why they failed. Unlike the uncontrollable, wet, chemical etch process, the DFAS IC chip decapitation process is 100% controllable by the operator through a Graphic User Interface (GUI). Utilizing the laser equipped DFAS, the operator can select a specific area to examine instead of dissecting the whole chip as chemical and mechanical etchers must do.

Traditionally, diamond saws were used for processes commonly used in failure analysis. This process is very slow requiring a significant amount of time for additional polishing due to the large standoff required from the cut, and still does not guarantee that the sample will not be damaged. The DFAS utilizes a Fonon's laser wafer ablation process to provide an extremely accurate dissection without damaging the sample.

[The FiberTower™ DFAS](#) also offers a laser spectrometry option to provide a detailed report of all the materials as they are being processed. This feature allows the operator to find inconsistencies within the compound, flow settlement, and contaminants, and provides detail report of the exact characteristics of the mold compound. Improvements to the FiberTower™ DFAS include the use of scan servos with position feedback for higher accuracy and scan see through capabilities for on time inspection.

Eliminating the majority of cost, sample damage, as well as long term health hazards associated with the use of chemicals, the DFAS performs chip failure analysis with unmatched safety, savings, accuracy and speed.

[About Fonon DSS:](#) A division of [Fonon Technology International](#), the world renowned inventor and manufacturer of Zero Width Laser Cutting Technology™, Fonon DSS focuses on the

semiconductor and flat panel display industries utilizing the patented Zero Width Laser Cutting Technology™ (ZWLCT™) to create products with the highest level of precision. Fonon DSS provides state-of-the-art laser scribing, laser dicing and fiber laser marking solutions to customers in the Flat Panel Display (FPD), Semiconductor and Electronics industries throughout the world. For more information, visit <http://www.fonondss.com> or call 407-829-2613.

To remove your name from our mailing list, please [click here](#). Questions or comments? Email us at info@fonondss.com or call 407-829-2613. Copyright 2007 Fonon DSS. All Rights Reserved.

Fonon DSS products and product names are either trademarks or registered trademarks of Fonon DSS. All other trademarks or registered trademarks are the property of their respective intellectual property owners.